Getting Started With MSP MCUs With CapTIvate™ Technology

MSP430FR2633, MSP430FR2533, MSP430FR2632, MSP430FR2532

This getting started guide provides information on where to find documentation and collateral for MSP MCUs with CapTIvate™ technology.

1 Introduction

The latest documentation for MSP MCUs with CapTIvate technology is available online. The following links are shortcuts to specific topics in the online version.

- Introduction
  - Capacitive sensing basics
  - Introduction to CapTIvate technology
  - Differences between MSP MCUs with capacitive touch I/Os and CapTIvate technology
- Getting started with CapTIvate technology
  - Silicon
    - MSP430FR263x, MSP430FR253x data sheet
    - MSP430FR2633 errata sheet
    - MSP430FR2533 errata sheet
    - MSP430FR2632 errata sheet
    - MSP430FR2532 errata sheet
  - Tools
    - CapTIvate MCU development kit
      - CAPTIVATE-BSWP self-capacitance sensor board
      - CAPTIVATE-PHONE mutual-capacitance sensor board
      - CAPTIVATE-PROXIMITY proximity sensor board
    - CapTIvate technology with metal-touch capacitive sensor
  - Software
    - CapTIvate design center GUI
    - CapTIvate software library
  - Installation Procedure
    - For TI Code Composer Studio™ software
    - For IAR Embedded Workbench™ software
  - CapTIvate technology out-of-the-box experience

- Advance design guides
  - CapTIvate technology hardware design guide
  - Designing for ultra-low power
  - Designing for noise immunity
  - Designing for moisture
  - Designing for proximity
  - IEC reference design

Revision History

Changes from November 7, 2015 to February 11, 2016	Page
• Changed link on "Differences between MSP MCUs with capacitive touch..." list item	1
• Changed links in the "Silicon" list item	1

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265